

Features

- Trench Power LV MOSFET Technology
- High Speed Switching
- High Density Cell Desihn for Low $R_{DS(on)}$
- Epoxy Meets UL 94 V-0 Flammability Rating
- Moisture Sensivity Level 1
- Halogen Free . “Green” Device (Note 1)
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

Maximum Ratings

- Operating Junction Temperature Range : -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 39°C/W Junction to Ambient^(Note 2)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltlage	V_{GS}	±25	V
Continuous Drain Current	I_D	$T_A=25^\circ\text{C}$	-12 A
		$T_A=70^\circ\text{C}$	-10 A
Pulsed Drain Current ^(Note 3)	I_{DM}	-55	A
Single Pulse Avalanche Energy ^(Note 4)	E_{AS}	105	mJ
Total Power Dissipation ^(Note 5)	P_D	3.2	W

Note: 1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

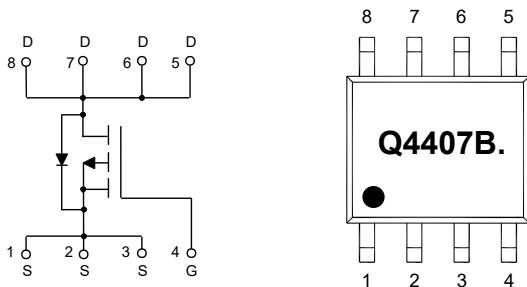
2.The Value of $R_{\theta JA}$ is Measured with the Device Mounted on 1in² FR-4 Board with 2oz. Copper, in a Still Air Environment with $T_A=25^\circ\text{C}$. The Value in Any Given Application Depends on the User's Specific Board Design.

3.Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.

4.Repetitive Rating, Pulse Width Limited by Junction Temperature $T_{J(MAX)}=150^\circ\text{C}$. Ratings are Based on Low Frequency and Duty Cycles to Keep Initial $T_J=25^\circ\text{C}$.

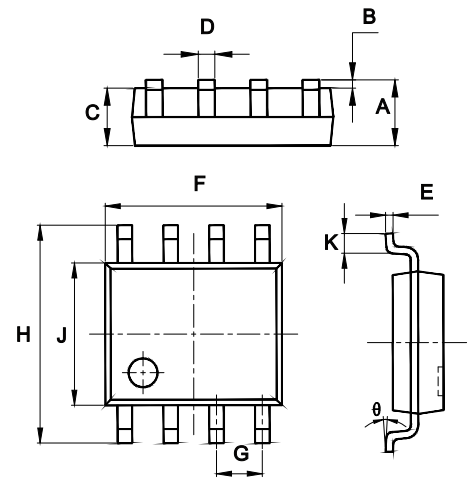
5.The Power Dissipation P_D is Based on $T_{J(MAX)}=150^\circ\text{C}$, Using ≤ 10s Junction-to-Ambient Thermal Resistance.

Internal Structure and Marking Code



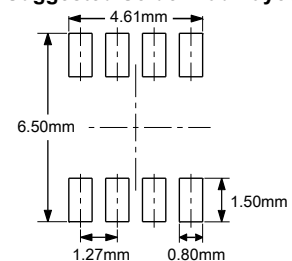
P-CHANNEL MOSFET

SOP-8



DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.053	0.069	1.35	1.75	
B	0.004	0.010	0.10	0.25	
C	0.053	0.061	1.35	1.55	
D	0.013	0.020	0.33	0.51	
E	0.007	0.010	0.17	0.25	
F	0.185	0.200	4.70	5.10	
G	0.050		1.270		TYP.
H	0.228	0.244	5.80	6.20	
J	0.150	0.157	3.80	4.00	
K	0.016	0.050	0.40	1.27	
θ	0°	8°	0°	8°	

Suggested Solder Pad Layout



Electrical Characteristics @ 25°C (Unless Otherwise Specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-30			V
Gate-Source Leakage Current	I_{GSS}	$V_{DS}=0V, V_{GS}=\pm 25V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-30V, V_{GS}=0V$			-1	μA
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.2	-1.8	-2.8	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=-20V, I_D=-12A$		9	10.5	m Ω
		$V_{GS}=-10V, I_D=-12A$		10.2	12.5	
		$V_{GS}=-6V, I_D=-10A$		12.3	16.5	
		$V_{GS}=-4.5V, I_D=-10A$		16	25	
Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_S=-12A$		-0.8	-1.2	V
Continuous Body Diode Current	I_S				-12	A
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS}=-15V, V_{GS}=0V, f=1MHz$		2050		pF
Output Capacitance	C_{oss}			355		
Reverse Transfer Capacitance	C_{rss}			301		
Switching Characteristics						
Total Gate Charge	Q_g	$V_{DS}=-15V, V_{GS}=-10V, I_D=-12A$		29.8		nC
Gate-Source Charge	Q_{gs}			4.7		
Gate-Drain Charge	Q_{gd}			10		
Turn-On Delay Time	$t_{d(on)}$	$V_{GS}=-10V, V_{DD}=-15V, I_D=-1A, R_{GEN}=2.5\Omega$		14		ns
Turn-On Rise Time	t_r			12		
Turn-Off Delay Time	$t_{d(off)}$			26		
Turn-Off Fall Time	t_f			10		

Curve Characteristics

Fig. 1 - Typical Output Characteristics

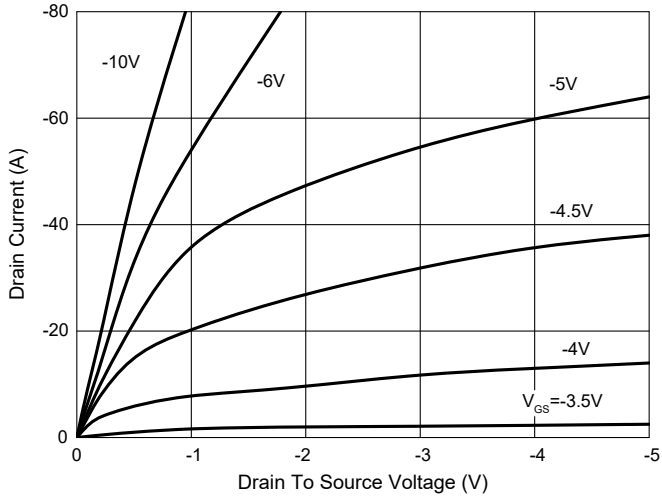


Fig. 2 - Transfer Characteristics

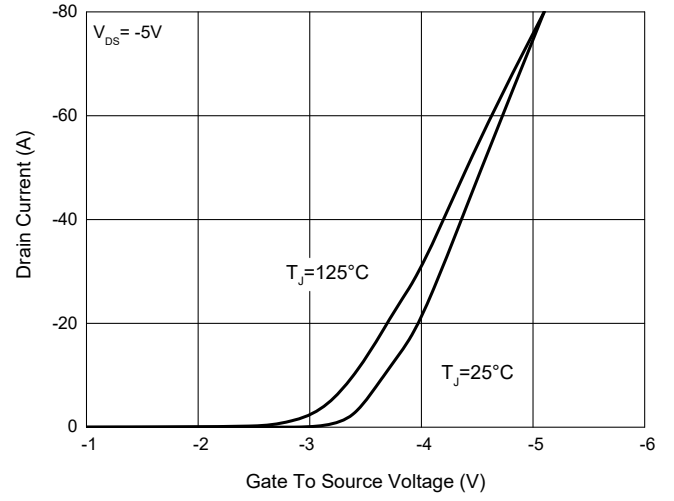


Fig. 3 - Capacitance Characteristics

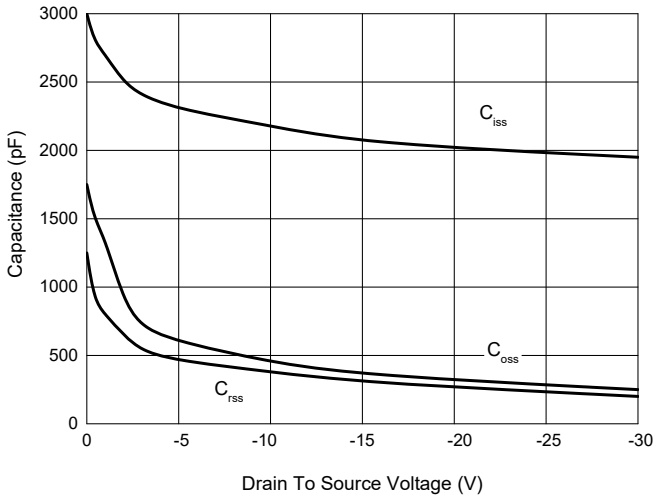


Fig. 4 - $R_{DS(ON)} - I_D$

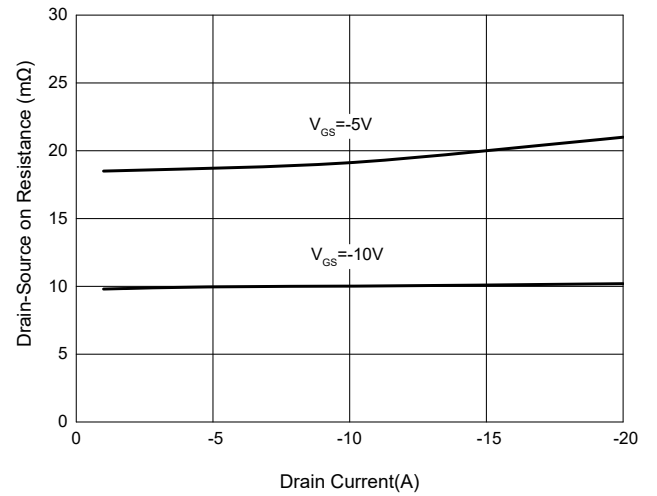


Fig. 5 - Total Gate Charge Characteristics

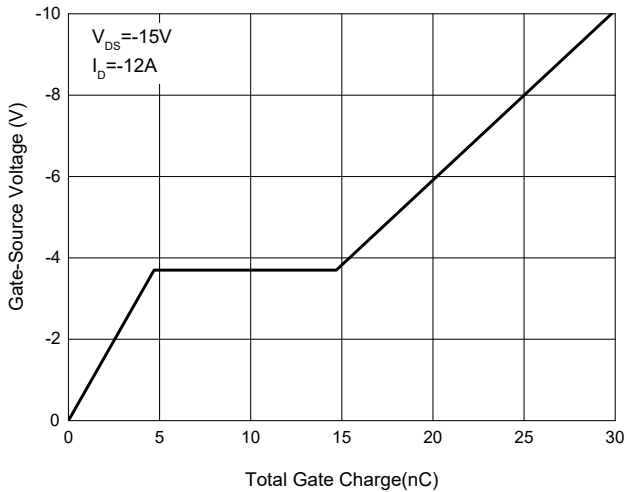
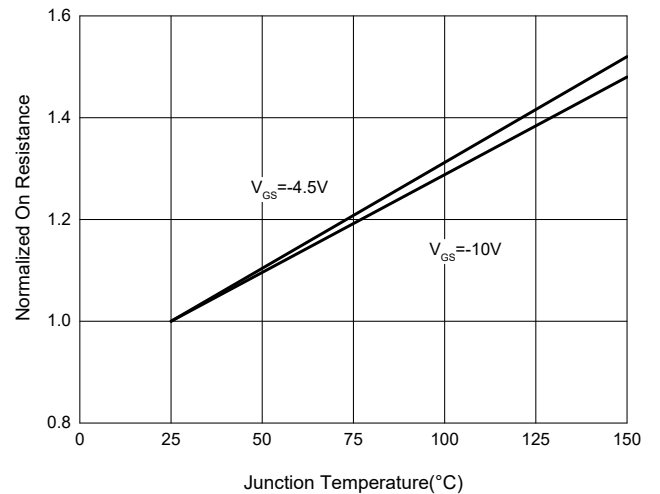
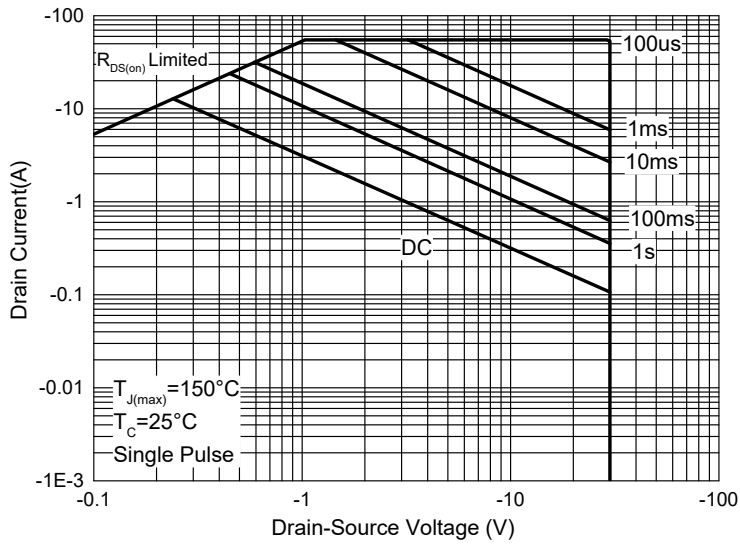


Fig. 6 - Normalized On Resistance Characteristics



Curve Characteristics

Fig. 7 - Safe Operation Area



Ordering Information

Device	Packing
Part Number-TP	Tape&Reel: 4Kpcs/Reel

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